_ AS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions. Material Composition Declaration with lower level parts, the declaration encompasses all lower level materials for which the manufacturer with lower level parts, the declaration encompasses all lower level materials for which the manufacturer engineering responsibility. Adobe Reader version 7.0.5 is required to complete this declaration.					e manufacturer has				
		PC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x		Form Type *		Declaration Class *				
Su	pplier Information									
Company Name *		Company Unique ID	Unique ID Authority	Response Dat	Response Date *		ument ID			
Contact Name *		Title - Contact	Phone - Contact *	Email - Contact *						
Authorized Representative		ve * Title - Representative	Phone - Representative *	Email - Repres	Email - Representative *		Supplier Comments or URL for Additional Information			
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type	
	Alternate Recommenda	ation			Alternate	Item Comments				

Manufacturing Information section intentionally omitted.

this form to a file	Import fields from a file into this form	Clear all of the fields on this form	form to prevent changes					
RoHS Material Co	omposition Declaration		Declaration Type *					
	S Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous brominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by ma			ated Biphenyls (PBB),				
RoHS Declaration *			Supplier Acceptance					
	clared item does not contain RoHS restricted substances per the definition at will appear below. Check all applicable exemptions.	pove except for defined RoHS exemptions, the	en select the corresponding respon	se in the RoHS Declaration				
1. Mercury in compact f	fluorescent lamps not exceeding 5 mg per lamp.	7c. Lead in electronic ceramic parts (e.g. pie	zoelectronic devices).					
2a. Mercury in straight f halophosphate lamps	fluorescent lamps for general purposes not exceeding 10 mg. in	8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices).						
2b. Mercury in straight f lamps with a normal life	fluorescent lamps for general purposes not exceeding 5 mg. in triphosphate etime	Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators						
2c. Mercury in straight f lamps with long lifetime	fluorescent lamps for general purposes not exceeding 8 mg. in triphosphate	10a. Deca BDE in polymeric applications						
3. Mercury in straight flu	uorescent lamps for special purposes.	10b. Lead in lead/bronze bearing shells and	bushes					
4. Mercury in other lamp	ps not specifically mentioned in this list.	11. Lead used in compliant pin connector systems.						
5. Lead in glass of catho	ode ray tubes, electronic components and fluorescent tubes.	12. Lead as a coating material for a thermal conduction module c-ring.						
6a. Lead as an alloying	element in steel containing up to 0.35% lead by weight.	13a. Lead in optical and filter glass.						
6b. Lead as an alloying	element in aluminum containing up to 0.4% lead by weight.	13b. Cadmium in optical and filter glass.						
6c. Lead as an alloying	element in copper containing up to 4% lead by weight.	14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight .						
7a. Lead in high melting weight or more lead).	g temperature type solders (i.e. lead based solder alloys containing 85% by	15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.						
	servers, storage and storage array systems, network infrastructure equipment transmission as well as network management for telecommunications.							
Declaration Signa	ature							
	lete all of the required fields on all pages of this form. Select the "Acuired by the Requester) and click on Submit Form to have the form ret		-down. This will display the sign	nature area. Digitally sign				
Supplier Digital Signa	ature							

Joint Industry Guide (JIG) Material Composition Declaration for Electronic Products

Instructions: Declare whether the item substances exceed the threshold levels shown in the table and report accordingly. Where threshold levels include the words "intentionally added", substances must be declared if they are added intentionally, regardless of threshold level. For each RoHS substance, identified with dual asterisks (**), report the worst case PPM at the homogeneous material level and optionally the total weight of the substance in the item. For all remaining (non-RoHS) JIG A & B substances, and any additional substances, report the total weight and optionally the PPM at the part level for each item.

JIG	Category Name	Threshold Level	Above Threshold Level?	If yes, enter total weight and worse case PPM		eight and PPM	Description of Use
Level	As defined in the Joint Industry Guide	Intentionally added or PPM	Yes/No	Weight UoM PPM		PPM	

OTHER Material Composition Declaration

Requester Instructions: The requester can optionally include additional substances that must be declared for the item on this form. This is in addition to JIG Level A and JIG Level B substances. The requester should enter additional substances as well as the threshold levels that specify the substance at the item level.

Supplier Instructions: Explicitly declare whether the item exceed the threshold level by selecting Yes or No. If the maximum concentration of any substance exceeds the threshold levels defined by the requester, then the substance content must be reported in total weight and/or worst case PPM, along with a description of material use.

JIG	Category Name	Threshold Level
Other	As defined by the Requester	Defined by the Requester